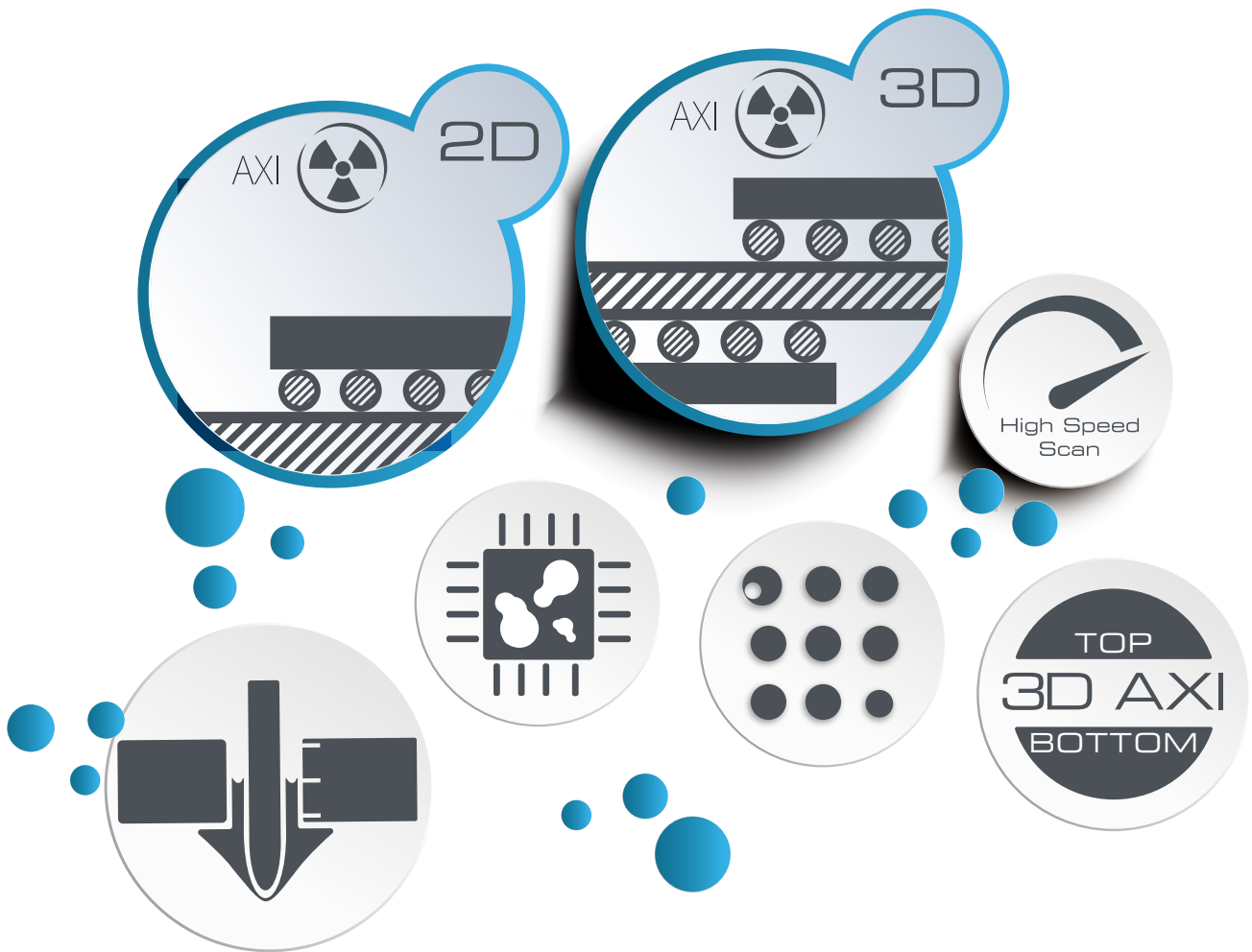




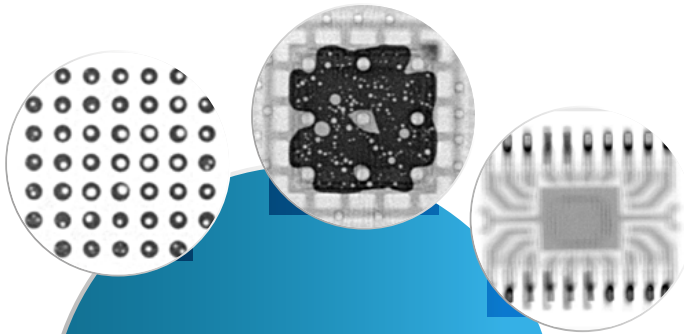
AXI · Technology

X-ray inspection XLine · 3D, XLine · 2D



- 3D X-ray inspection of double sided assembled PCBs
- 2D X-ray inspection of single sided assembled PCBs
- fast PCB handling (5 seconds)
- low-maintenance system concept
- IPC-orientated inspection
- MES connection via plug-ins



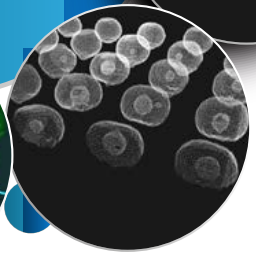
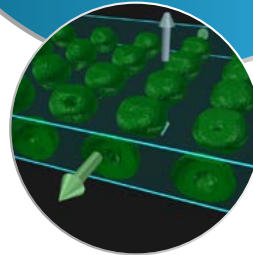
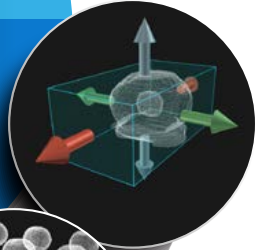


AXI · X-ray inspection

- all-over solder joint check using 3D AXI for IPC-compliant checking of solder joints
- hidden and visible solder joints are reliably tested using 3D AXI

AOI · optical inspection

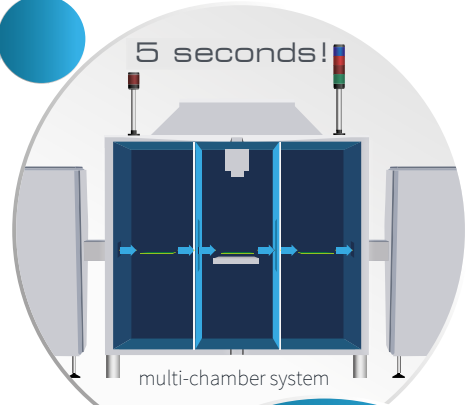
- test tasks that cannot be performed with 3D AXI are covered by optional AOI module
- polarity, OCR, colour recognition, code reading, selective solder joint inspection



Digital maintenance app

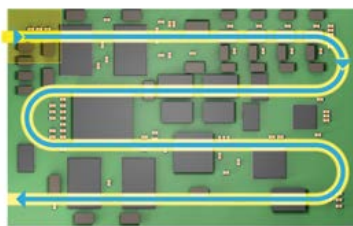
- Digital maintenance plan
- Usage-based maintenance
- Predictive maintenance based on meters

5 seconds!



Fast 3D image capture

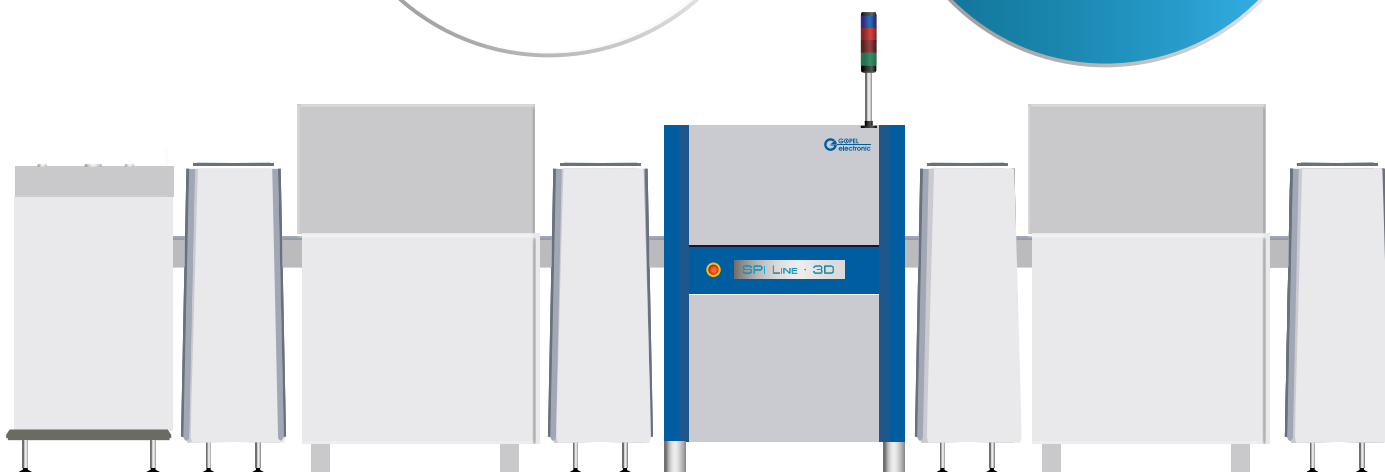
- fast 3D X-ray image capture in motion
- scanning image capture enables X-ray inspection of complete PCB
- 3D X-ray image reconstruction for inspection of the assembly layer by layer



scanning X-ray image capture

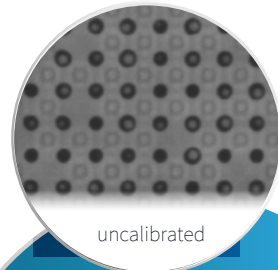
Fast PCB handling

- using a multi-chamber system with double shutters
- parallel loading, inspection and unloading



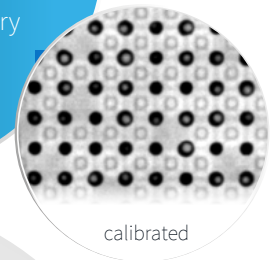
Unique detector

- multi-angle detector (3rd generation) with extremely high operating life



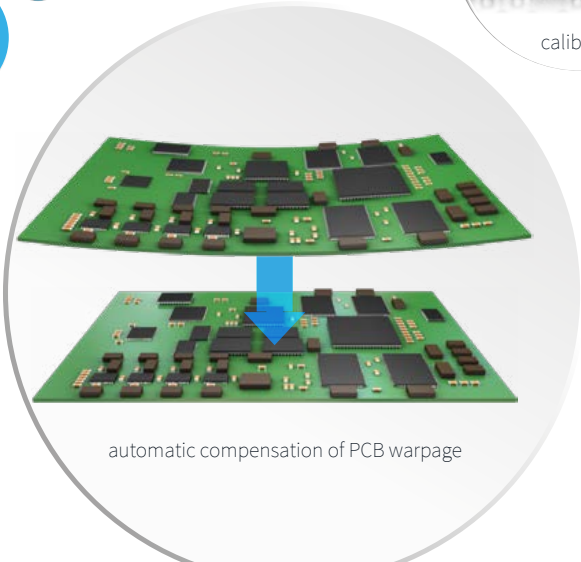
Calibration

- complete geometric and grey-value calibrated
- no distorted X-ray images
- uniform component library can be used



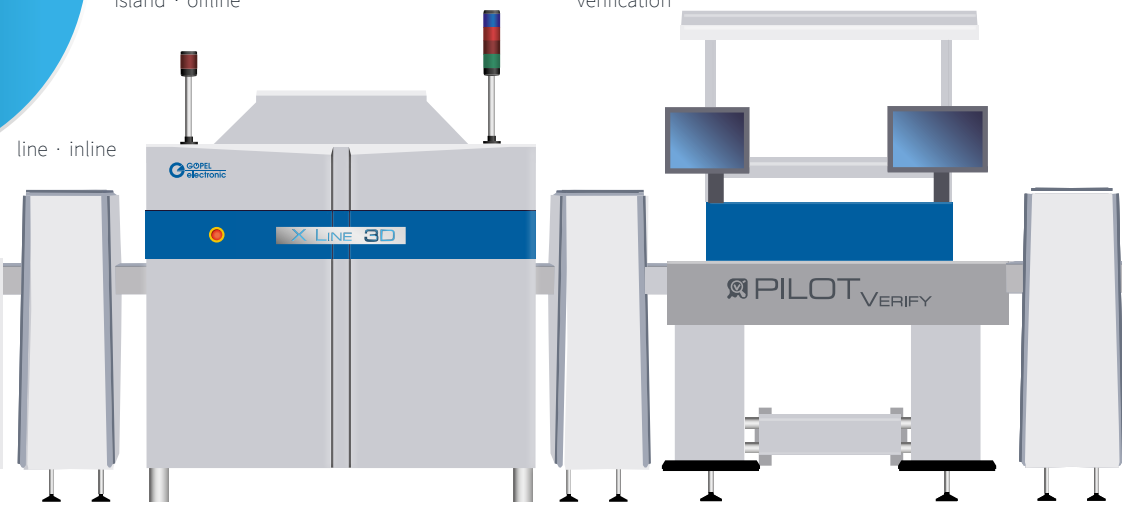
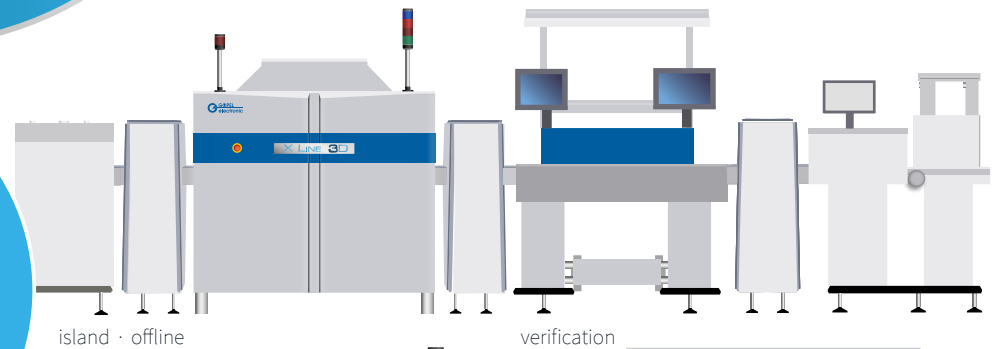
Typical applications

- BGA inspection
- QFN, DFN and LGA inspection
- void inspection
- inspection of the rear solder meniscus of gullwing pins
- full inspection of the two menisci on J-lead pins
- THT/THR barrel fill, solder volume
- inspection of multiple assembly levels (package-on-package, piggy-back modules)



System usage

- as an island system (offline) or directly in the production line (inline)



PILOT AXI Software



PILOT AXI software

- fast and intuitive creation of test programs with test program wizard
- AXI component library
- data import functionality (ODB++, GenCAD, Gerber, pick and place)
- integrated debugging statistics for fast optimisation of inspection programs
- full offline programming away from the production line
- intelligent data management for storing test results
- MES interfaces via PILOT Connect (bidirectional, unidirectional)



- THT/THR barrel fill inspection



- 3D X-ray inspection of face-to-face assembly

PILOT INSPECT



PILOT Inspect

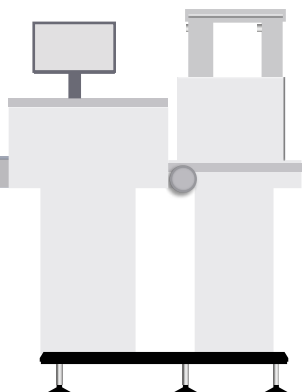
- intuitive operator software with apps
- machine can be operated by touch

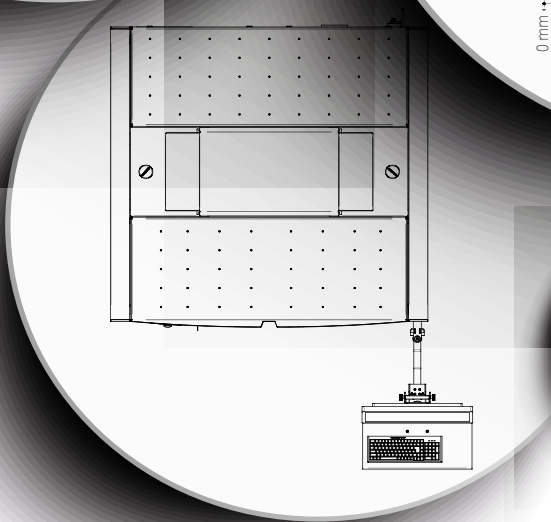
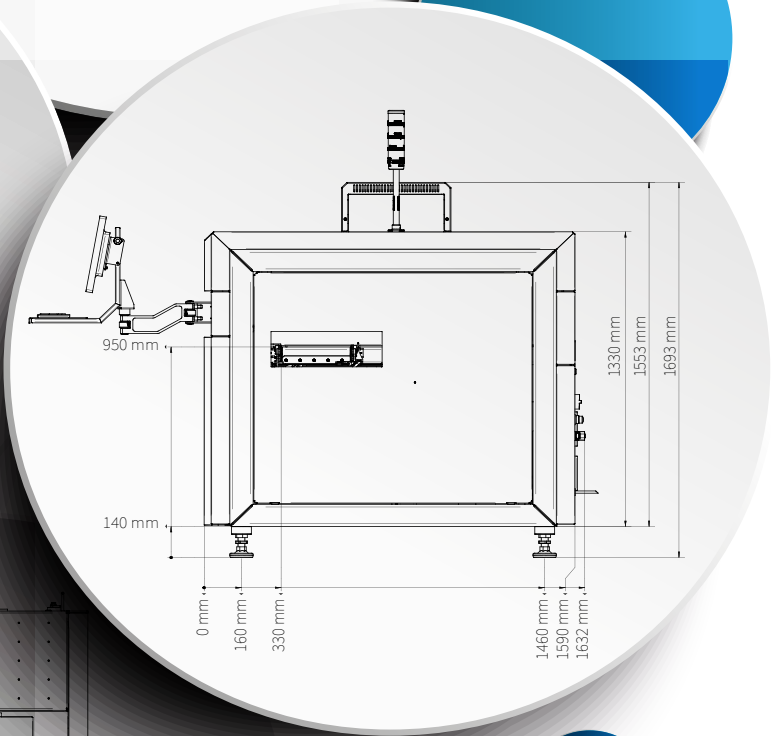
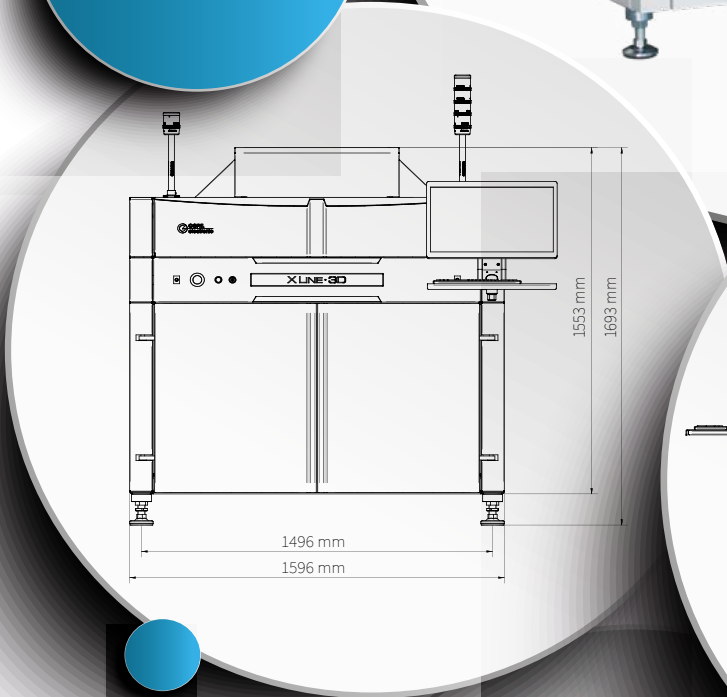
PILOT Connect software

all the data stored central

- connection of all the inspection data from SPI, AOI and AXI
- repair station with a clear visualisation of the AOI, AXI and SPI test results at the same time
- opportunities for process analysis and optimisation by statistically linking of the inspection data
- interfaces to MES and traceability systems
- integration of external inspection systems
- integrated user management for all related systems and software modules
- data maintenance tools

PILOT CONNECT





Models	
versions	X Line · 3D
	X Line · 3D

System	
inline interface	SMEMA, Siemens, HERMES
device connections	230 VAC, 1.4 kVA, 6 bar compressed air, < 25 NI/min *
dimensions (w x d x h)	base unit: 1596 mm x 1540 mm x 1470 mm
	device with tube tower: 1596 mm x 1540 mm x 1720 mm
weight	approx. 2.6 t

PCB handling	
transport height	850 mm ± 25 mm
	950 mm ± 25 mm
width adjustment	automatic
PCB size (l x w)	max. 435 mm x 400 mm
	min. 60 mm x 50 mm
PCB thickness	0.5 mm – 4 mm
PCB edge clearance	≥ 3 mm
PCB weight	≤ 1.5 kg, optional 5 kg
PCB warpage	automatic compensation (laser)
component clearance of PCB	below: 65 mm
	above: max. 40 mm **
handling time	approx. 5 s (parallel loading/unloading and inspection)

* referring to 45 sec cycle time, ** depending on detail resolution

X-ray technology	
tube type	maintenance free, sealed micro-focus X-ray tube
tube voltage	max. 130 kV
tube current	max. 300 µA
tube output	max. 39 W
detector type	MultiAngle Detector 3, real-time image capture from different angles
grey-scale resolution	12 bits
detail resolution	up to 6 µm* (typical 10 – 15 µm)
3D inspection speed	up to 100 cm ² /s
calibration	geometric and grey-value calibration
z-axis adjustment	customisable geometrical magnification by means of motorised vertical positioning of the tube
X-ray protection	in accordance with the German X-ray Ordinance RöV, three segments, radiation-proof

* depending on upper component clearance

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